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(54) **LIGHT-EMITTING DIODE PACKAGE**

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(57) **ABSTRACT**

A light-emitting diode package includes a substrate, a light-emitting diode chip mounted on the substrate, a phosphor surrounding a side surface and an upper surface of the light-emitting diode chip, a light conversion structure disposed on the phosphor, and a transparent element disposed between the phosphor and the light conversion structure.

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